

# LNA2603F (LN155)

## GaAs Infrared Light Emitting Diode

For optical control systems

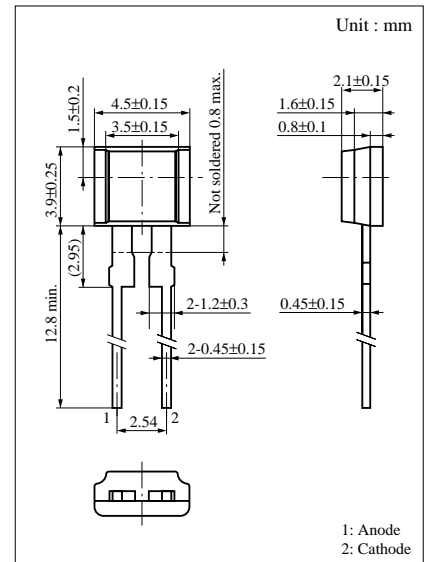
### ■ Features

- High-power output, high-efficiency :  $P_O = 6 \text{ mW (typ.)}$
- Emitted light spectrum suited for silicon photodetectors :  
 $\lambda_p = 940 \text{ nm (typ.)}$
- Long lifetime, high reliability
- Thin side-view type package

### ■ Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Ratings	Unit
Power dissipation	$P_D$	160	mW
Forward current (DC)	$I_F$	100	mA
Pulse forward current	$I_{FP}^*$	1.5	A
Reverse voltage (DC)	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

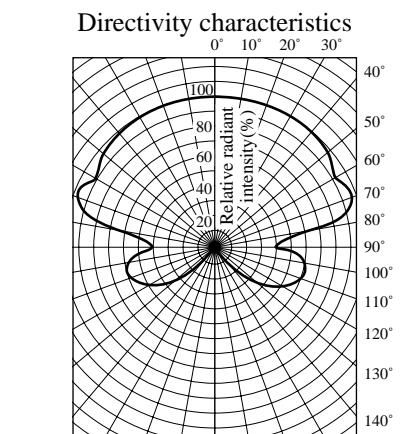
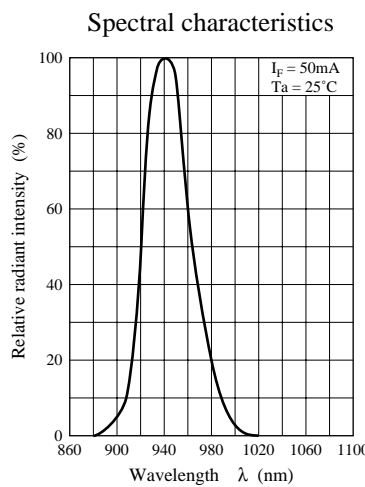
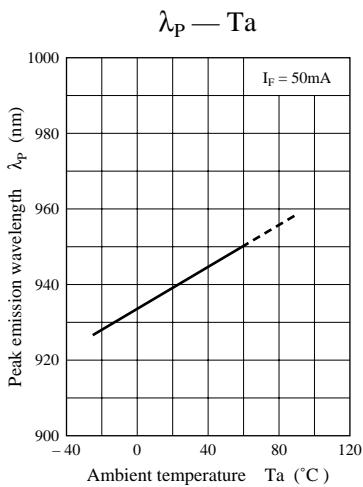
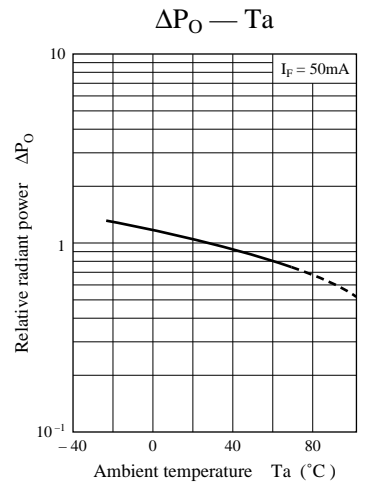
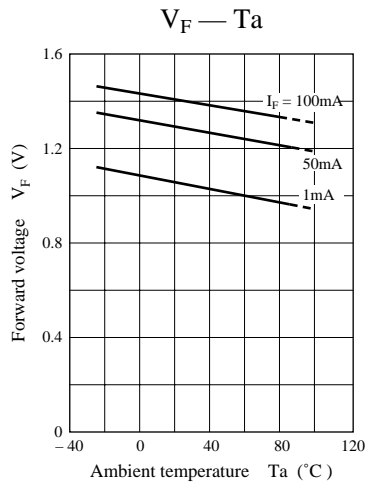
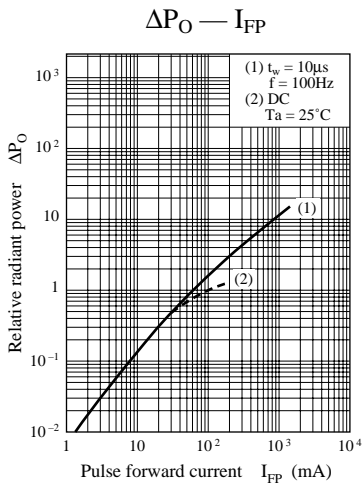
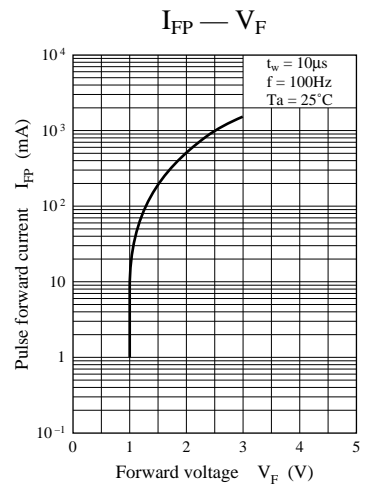
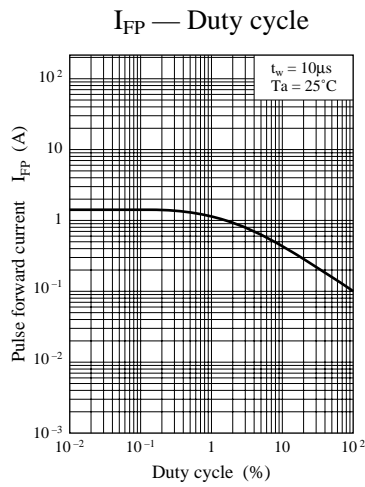
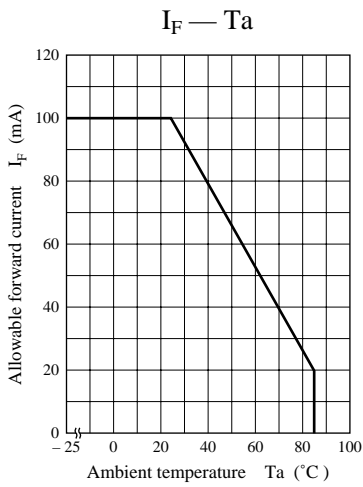
\*  $f = 100 \text{ Hz}$ , Duty cycle = 0.1 %



### ■ Electro-Optical Characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	min	typ	max	Unit
Radiant power	$P_O$	$I_F = 50\text{mA}$	3	6		mW
Peak emission wavelength	$\lambda_p$	$I_F = 50\text{mA}$		940		nm
Spectral half band width	$\Delta\lambda$	$I_F = 50\text{mA}$		50		nm
Forward voltage (DC)	$V_F$	$I_F = 100\text{mA}$		1.3	1.6	V
Reverse current (DC)	$I_R$	$V_R = 3\text{V}$			10	$\mu\text{A}$
Capacitance between pins	$C_t$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$		45		pF
Rise time	$t_r$	$I_{FP} = 100\text{mA}$		1		$\mu\text{s}$
Fall time	$t_f$			1		$\mu\text{s}$
Half-power angle	$\theta$	The angle in which radiant intensity is 50%		80		deg.

Note) The part number in the parenthesis shows conventional part number.



# Caution for Safety

 **DANGER**

Gallium arsenide material (GaAs) is used in this product.

Therefore, do not burn, destroy, cut, crush, or chemically decompose the product, since gallium arsenide material in powder or vapor form is harmful to human health.

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